

L Number	Hits	Search Text	DB	Time stamp
-	1	(electrolytic near4 plating) and (feeder adj film)	USPAT; US-PGPUB	2002/11/26 18:05
-	3227	(electrolytic near4 plating) and substrate	USPAT; US-PGPUB	2002/11/22 11:07
-	4669	electrolytic near4 plating	USPAT; US-PGPUB	2002/11/22 13:52
-	3142	electrolytic adj plating	USPAT; US-PGPUB	2002/11/22 13:52
-	3142	electrolytic adj plating	USPAT; US-PGPUB	2002/11/22 13:52
-	2452	(electrolytic adj plating) and (substrate or semiconductor)	USPAT; US-PGPUB	2002/11/22 13:53
-	37	tonami.in.	USPAT; US-PGPUB	2002/11/22 14:06
-	3	tonami.in. and Yoshiyuki	USPAT; US-PGPUB	2002/11/22 14:06
-	37	tonami.in.	USPAT; US-PGPUB	2002/11/22 14:06
-	485	tonami.in.	JPO; DERWENT	2002/11/22 14:06
-	0	tonami.in. and Yoshiyuki	JPO; DERWENT	2002/11/22 14:07
-	34	tonami.in. and Yoshiyuki	JPO; DERWENT	2002/11/22 14:13
-	2143	216/13.cccls. or 216/18.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:15
-	23	(216/13.cccls. or 216/18.cccls.) and 216/40.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:15
-	1	((216/13.cccls. or 216/18.cccls.) and 216/40.cccls.) and 216/100.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:16
-	147	(216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:16
-	0	((216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.) and 216/40.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:16
-	11	((216/13.cccls. or 216/18.cccls.) and 205/\$.cccls.) and 216/100.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:18
-	1278	205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:19
-	35	(205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.) and taper\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 14:19
-	1	((205/80.cccls. or 205/123.cccls. or 205/125.cccls. or 205/223.cccls.) and taper\$4) and lift-off	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/22 15:37

	118	205/80.cccls.	USPAT; US-PGPUB	2002/11/22 15:09
	121	205/169.cccls.	USPAT; US-PGPUB	2002/11/22 15:10
	0	(205/80, 123, 157, "169" and "223").cccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:40
	0	(205/80,123,157,169,223).cccls. and (electrolytic adj plating adj electrode)	USPAT; US-PGPUB	2002/11/22 15:41
	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
	0	c25d05/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
	18607	c25d005/\$.ipc.	JPO; DERWENT	2002/11/22 16:45
	0	c25d005/\$.ipc. and (electrolytic near4 plating) and (feeder adj film)	JPO; DERWENT	2002/11/22 16:46
	651	c25d005/\$.ipc. and (electrolytic near4 plating)	JPO; DERWENT	2002/11/22 18:46
	55	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base) and (cu or copper or ti or titanium)	JPO; DERWENT	2002/11/22 16:51
	285	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4)	JPO; DERWENT	2002/11/22 17:38
	28	(c25d005/\$.ipc. and (electrolytic near4 plating)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	JPO; DERWENT	2002/11/22 18:41
	3874	(205/\$ or 216/\$).cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:20
	1492	205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)	USPAT; US-PGPUB	2002/11/22 18:24
	1410	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:23
	1297	205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)	USPAT; US-PGPUB	2002/11/22 18:28
	149	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$8)	USPAT; US-PGPUB	2002/11/22 18:32
	148	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wire\$4 near7 form\$6)	USPAT; US-PGPUB	2002/11/22 18:32
	168	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and (wir\$4 near7 form\$5)	USPAT; US-PGPUB	2002/11/22 18:34
	43	(205/\$.cccls. and (feed\$4 or electrode or wire\$4 or base or conduct\$4) near7 (partial\$4)) and ((wire or wiring) near7 (formation or pattern or fabrication))	USPAT; US-PGPUB	2002/11/27 09:52
	1312	(205/80,123,125,223,157).cccls.	USPAT; US-PGPUB	2002/11/22 18:40
	1868	(216/13,18,40,100).cccls.	USPAT; US-PGPUB	2002/11/22 18:41
	3103	((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)	USPAT; US-PGPUB	2002/11/22 18:41
	1015	((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)	USPAT; US-PGPUB	2002/11/22 18:43
	964	((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117	USPAT; US-PGPUB	2002/11/22 18:44

	99	(((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 15:04
	99	(((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/23 11:59
	99	(((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:55
	1	4866008.pn.	USPAT; US-PGPUB	2002/11/23 17:09
	103	205/186.cccls.	USPAT; US-PGPUB	2002/11/27 09:45
	361	(((((205/123,125,223,157,186).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/26 18:54
	99	(((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating)	USPAT; US-PGPUB	2002/11/26 18:59
	263	(((((205/123,125,223,157,186).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic\$4 or electrodeposit\$4) not (((((205/80,123,125,223,157).cccls.) or ((216/13,18,40,100).cccls.)) and (feed\$2 or electrode or wire\$4 or base or conduct\$4) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117) and (electrolytic near4 plating))	USPAT; US-PGPUB	2002/11/26 18:56
	270	(205/186,123,125,223,157).cccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and @ad<20010117 and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 10:42
	19	205/186.cccls. and ((feed\$4 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (partial\$4 or mask or pattern))	USPAT; US-PGPUB	2002/11/27 10:34
	3	"2000008247"	JPO; DERWENT	2002/11/27 10:41
	22685	h011021/3205.ipc.	JPO; DERWENT	2002/11/27 10:41
	47	h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:48
	1	04262536.pn.	DERWENT	2002/11/27 14:29
	1	"04262536"	DERWENT	2002/11/27 14:30
	2	"04262536"	JPO; DERWENT	2002/11/27 15:10
	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 15:10

-	0	(205/186,123,125,223,157). and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:51
-	283	(205/186,123,125,223,157).ccls. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	USPAT; US-PGPUB	2002/11/27 15:56
-	384	(h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)	JPO; DERWENT	2002/11/27 15:55
-	337	(h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4))	JPO; DERWENT	2002/11/27 15:53
-	28	((h011021/\$).ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) not (h011021/3205.ipc. and ((feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed) near7 (pattern or mask\$4 or partial\$4)) and ((electrolytic near plating) or electroplating or electrodeposit\$4)) and ((remove or etch) near7 (feed\$2 or electrode or wire\$4 or base or conduct\$4 or seed))	JPO; DERWENT	2002/11/27 16:18
-	1	5550068.pn.	USPAT; US-PGPUB	2002/11/27 16:18